

2SA1034, 2SA1035

Silicon PNP epitaxial planar type

For low-frequency and low-noise amplification
Complementary to 2SC2405, 2SC2406

■ Features

- Low noise voltage NV
- High forward current transfer ratio h_{FE}
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	2SA1034	V_{CBO}	-35	V
	2SA1035		-55	
Collector-emitter voltage (Base open)	2SA1034	V_{CEO}	-35	V
	2SA1035		-55	
Emitter-base voltage (Collector open)	V_{EBO}	-5	V	
Collector current	I_C	-50	mA	
Peak collector current	I_{CP}	-100	mA	
Collector power dissipation	P_C	200	mW	
Junction temperature	T_j	150	$^\circ\text{C}$	
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$	

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

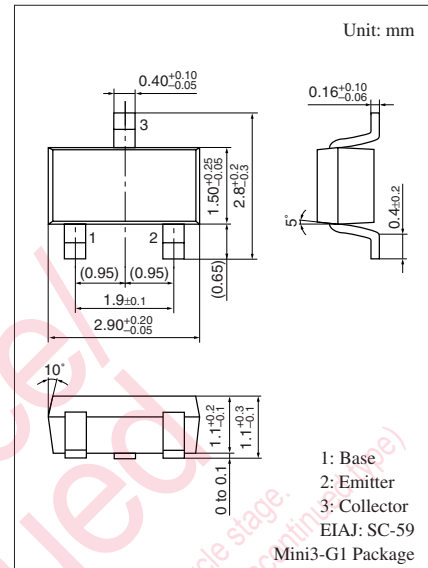
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	2SA1034	V_{CBO} $I_C = -10 \mu\text{A}$, $I_E = 0$	-35			V
	2SA1035		-55			
Collector-emitter voltage (Base open)	2SA1034	V_{CEO} $I_C = -2 \text{ mA}$, $I_B = 0$	-35			V
	2SA1035		-55			
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}$, $I_C = 0$	-5			V
Base-emitter voltage *1	V_{BE}	$V_{CE} = -1 \text{ V}$, $I_C = -100 \text{ mA}$		-0.7	-1.0	V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}$, $I_E = 0$			-0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10 \text{ V}$, $I_B = 0$			-1	μA
Forward current transfer ratio *2	h_{FE}	$V_{CE} = -5 \text{ V}$, $I_C = -2 \text{ mA}$	180		700	—
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = -100 \text{ mA}$, $I_B = -10 \text{ mA}$			-0.6	V
Transition frequency	f_T	$V_{CB} = -5 \text{ V}$, $I_E = 2 \text{ mA}$, $f = 200 \text{ MHz}$		200		MHz
Noise voltage	NV	$V_{CE} = -10 \text{ V}$, $I_C = -1 \text{ mA}$, $G_V = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega$, Function = FLAT			150	mV

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

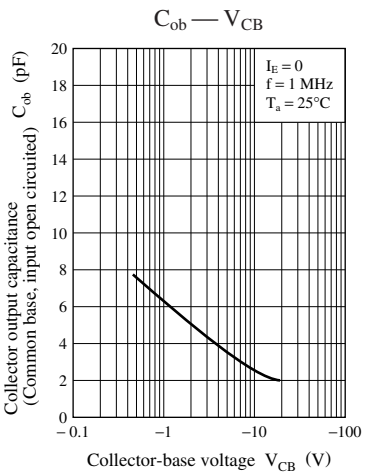
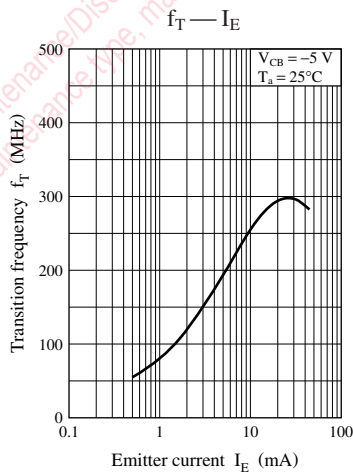
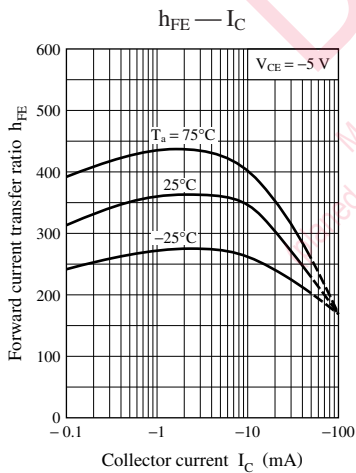
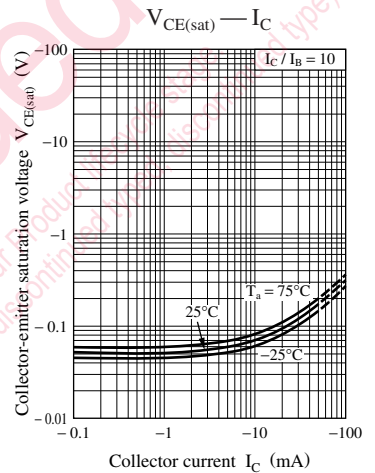
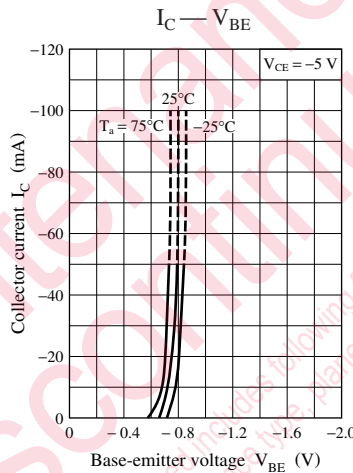
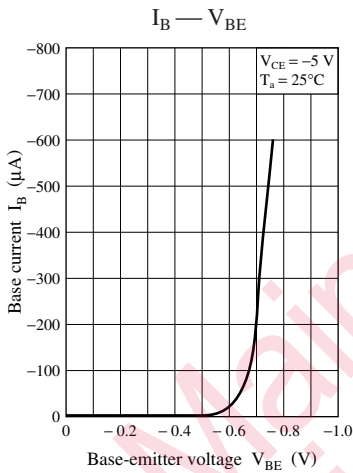
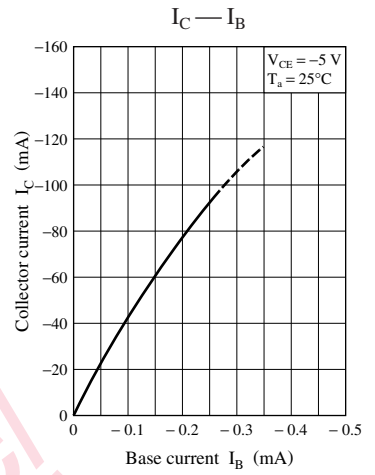
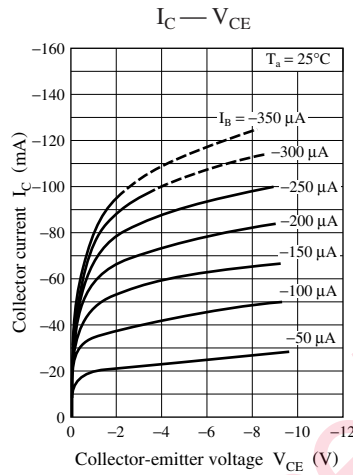
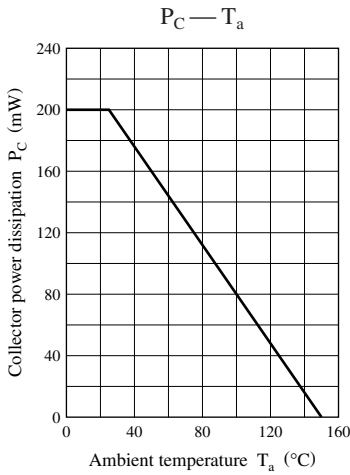
*2: Rank classification

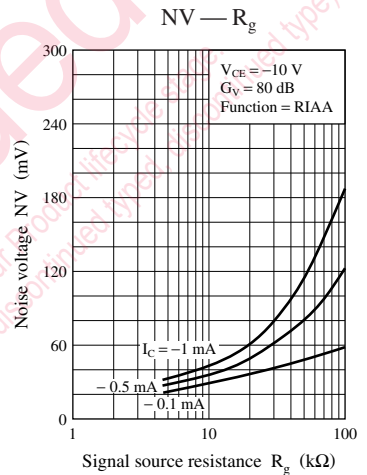
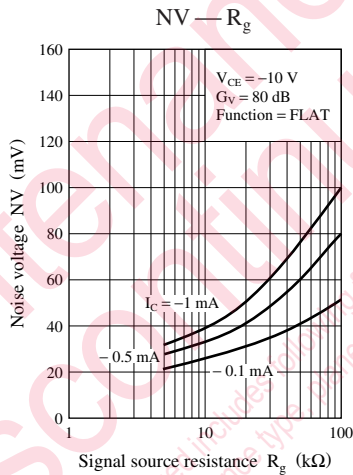
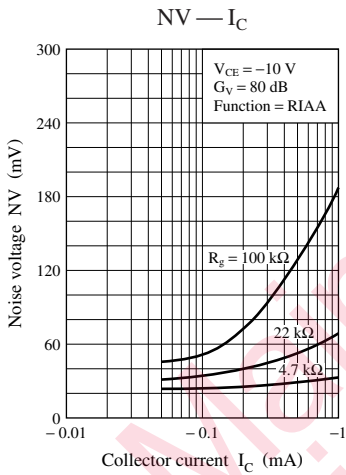
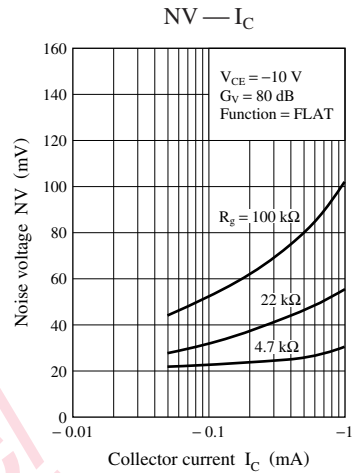
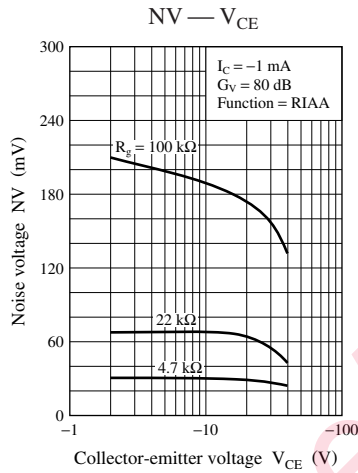
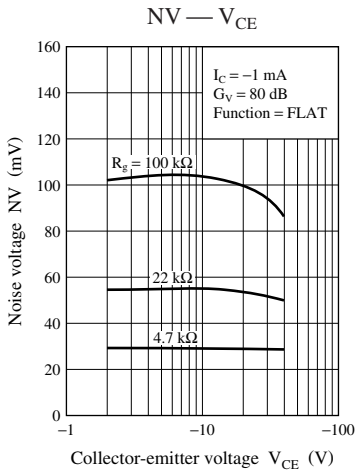
Rank	R	S	T
h_{FE}	180 to 360	260 to 520	360 to 700



Marking Symbol:

- 2SA1034: F
- 2SA1035: H





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